







DISCRIPTION

FEATURES

Ceramic core
High frequency design
Excellent Q values
Excellent SRF
High reliability
Excellent thermal stability

OPTIONS

Tape & Reel is Standard (Qty: 4.000 Pcs)
Bulk Packing Available for smaller quantites
Tolerance: K=10%, M=20% is Standard,
tighter Tolerance available (MOQ on request)

APPLICATIONS

Modems
Mobile Radios
Cordless Telephones
Global Positioning Systems
Telecommunications Systems

PHYSICAL CHARACTERISTICS

• Testing: (Equivalents acceptable) Inductance & Q-HP4195A + HP41951

SRF: HP8753C; RDC: 25°C

Operating Temperature : Ceramic -25°C ~ 85°C
 Pad metalization : Tungsten-nickel with gold flash
 Solder methods : Wave, Reflow, Vapor Phase
 Solderability : Max 260°C for 10 seconds

• Marking : EIA color code

APPD:

Pong

ELECTRICAL SPECIFICATIONS

Properties	Test conditions		Value	Unit	Tol.
Inductance		L	30,0	nH	see Site 2
Q factor		Q	37		min.
DC-resistance		DCR typ.		Ω	typ.
DC-resistance		DCR max.	0,144	Ω	max.
Self-Res. Freq.		SRF	2250	Mhz	min.
Test-Freq.			250	Mhz	
Rated Current		IDC	600	mA	max.
Saturation Current		Isat		mA	typ.

SMT WIRE-WOUND 1. This electronic component is meant to be used in general electronic equipment. Before the incorporation **CERAMIC CHIP** of this component into any equipment with higher and more reliable requirements such as aviation, aerospace, submarine, nuclear control, transportation, transportation signal, disaster prevention, medical, **INDUCTORS** public information network, etc. or if there is a possibility of injuries or damages to the human body, Edcon -Components must be informed before the stage of design-in. Evaluation checks for safety have to be Part No .: S12002-30N performed on each electronic components used in electrical circuits that require high safety and reliability functions. Customer: DRW: Chang CHKD Young MATL: Chu Chi DATE 25.10.2013

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Sheet



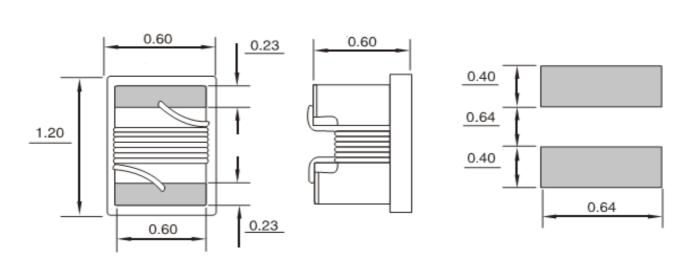






TECHNICAL INFORMATIONS

Dimensions (mm)



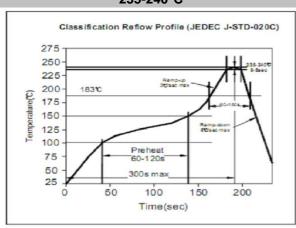
Ordering Information

Serie and Range				
S12002-30N				

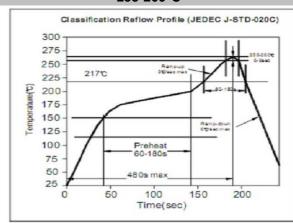
Tolerance	ROHS	Packing	
K	R	TR	

K = 10%	R = ROHS	BU = Bulk Ware
M = 20%	N = non ROHS	TR = Tape Reel
N = 30%		

Soldering Profile for Lead Free Soldering 235-240°C



Soldering Profile for Lead Free Soldering 255-260°C



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functions.

SMT WIRE-WOUND CERAMIC CHIP INDUCTORS

Part No.: **\$12002-30N**

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